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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10053963	01/22/2002	257	27	2841	

**APPLICANTS: Lunde Aron;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no	37829.0400
Verified and Acknowledged Examiners's initials		
TITLE : Die assembly and method for forming a die on a wafer		

U.S. DEPT. OF COMM. / PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg.
Primary Examiner		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
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